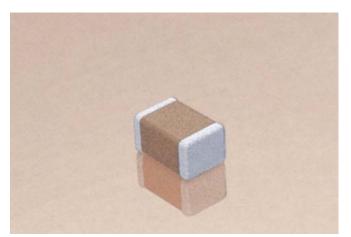
General Specifications



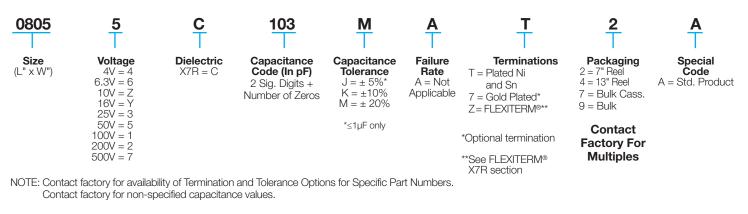


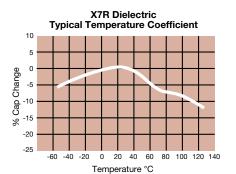
X7R formulations are called "temperature stable" ceramics and fall into EIA Class II materials. X7R is the most popular of these intermediate dielectric constant materials. Its temperature variation of capacitance is within $\pm 15\%$ from -55°C to +125°C. This capacitance change is non-linear.

Capacitance for X7R varies under the influence of electrical operating conditions such as voltage and frequency.

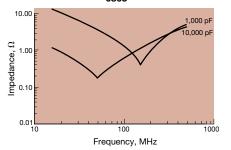
X7R dielectric chip usage covers the broad spectrum of industrial applications where known changes in capacitance due to applied voltages are acceptable.

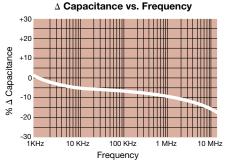
PART NUMBER (see page 2 for complete part number explanation)

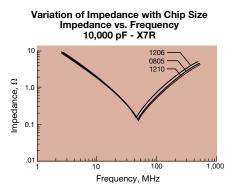


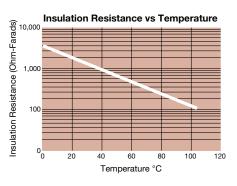




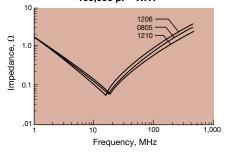








Variation of Impedance with Chip Size Impedance vs. Frequency 100,000 pF - X7R





Specifications and Test Methods

Parame	ter/Test	X7R Specification Limits	Measuring Conditions							
Operating Temp	perature Range	-55°C to +125°C	Temperature Cycle Chamber							
Capac		Within specified tolerance		-						
Dissipatio		\leq 2.5% for \geq 50V DC rating \leq 3.0% for 25V DC rating \leq 3.5% for 16V DC rating \leq 5.0% for \leq 10V DC rating	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 μF, 0.5Vrms @ 120Hz							
Insulation I	Pagiatanga	100,000MΩ or 1000MΩ - μF,	Charge device with							
Dielectric		whichever is less No breakdown or visual defects	120 ± 5 secs @ room temp/humidity Charge device with 300% of rated voltage fo 1-5 seconds, w/charge and discharge curren limited to 50 mA (max) Note: Charge device with 150% of rated voltage for 500V devices.							
	Appearance	No defects	Deflectio							
	Capacitance	<pre></pre>	Test Time: 3	30 seconds						
Resistance to	Variation	S ± 12 /0		7 1mm/sec						
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)								
	Insulation Resistance	\geq Initial Value x 0.3	90 n							
		\geq 95% of each terminal should be covered	Dip device in eutectic							
Solder	ability	with fresh solder	for 5.0 \pm 0.							
	Appearance	No defects, <25% leaching of either end terminal								
	Capacitance	<pre>< ±7.5%</pre>	•							
Resistance to Solder Heat	Variation	≤ ±1.570	 Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties 							
	Dissipation Factor	Meets Initial Values (As Above)								
	Insulation Resistance	Meets Initial Values (As Above)	Hours before measuring	g electrical properties.						
	Dielectric Strength	Meets Initial Values (As Above)								
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes						
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes						
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes						
Chicola	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes						
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 ± 2 hours at room temperature							
	Appearance	No visual defects								
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 rated voltage (≤ 10V) ir test chamber set at 125°C ± 2°C for 1000 hours (+48, -0) Remove from test chamber and stabilize at room temperature for 24 ± 2 hours							
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)								
	Insulation Resistance	\geq Initial Value x 0.3 (See Above)								
	Dielectric	Meets Initial Values (As Above)	before me	easuring.						
	Strength Appearance	No visual defects								
	Capacitance		Store in a test chamb							
	Variation	≤ ±12.5%	$85\% \pm 5\%$ relative hur							
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	(+48, -0) with rated	0 11						
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from cham room temperature	and humidity for						
	Dielectric Strength	Meets Initial Values (As Above)	24 ± 2 hours be	iore measuring.						



Capacitance Range



PREFERRED SIZES ARE SHADED

			•			•		CD																							
SIZ	SIZE 0201 0402						2 0603									0805							1206								
Soldering Reflow Only					Ref	low/W	lave 1	Reflow/Wave									Ref	low/W	lave			Reflow/Wave									
Packaging All Paper						II Pap		All Paper							Paper/Embossed							Paper/Embossed									
(L) Length	mm (in.)	0.	.60 ± 0. 024 ± 0.	03 1.00 ± 0.10				$\begin{array}{c} 1.60 \pm 0.15 \\ (0.063 \pm 0.006) \end{array}$							2.01 ± 0.20 (0.079 ± 0.008)							3.20 ± 0.20 (0.126 ± 0.008)									
(W) Width	mm		.30 ± 0.			$50 \pm 0.$		0.003 ± 0.000) 0.81 ± 0.15										.25 ± 0.1				1.60 ± 0.20									
	(in.))11 ± 0.			20 ± 0.					32 ± 0.				(0.049 ± 0.008)							(0.063 ± 0.008)									
(t) Terminal	mm		.15 ± 0.			$25 \pm 0.$					0.35 ± 0.15					0.50 ± 0.25								0.50 ± 0.25 (0.020 ± 0.010)							
	(in.)		106 ± 0.0			10 ± 0.		0.0	10		14 ± 0.0					40		20 ± 0.010)			000	0.0	1.40		<u>`</u>				500		
Сар	WVDC 100	10 A	16 A	25	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500		
(pF)	150	A	A	A																											
(pr)	220	Â	Â	Â			С																								
	330	A	A	A			C					G	G	G		J	J	J	J	J	J								K		
	470	Â	A				č					G	G	G		J	J	Ĵ	J	Ĵ	J								K		
	680	A	A				č					G	G	G		J	J	Ĵ	J	Ĵ	Ĵ								K		
	1000	Α	A				С					G	G	G		J	J	J	J	J	J								К		
	1500	А		1	1		С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	М		
	2200	Α					С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	M		
	3300	А				С	С					G	G			J	J	J	J	J	J		J	J	J	J	J	J	Μ		
	4700 A C C							G	G			J	J	J	J	J	J		J	J	J	J	J	J	M						
	6800	A			C	С						G	G			J	J	J	J	J	J		J	J	J	J	J	J	P		
Сар	0.010	A			С	С					_	G G	G			J	J	J	J	J	J		J	J	J	J	J	J	Р		
(µF	0.015 0.022				C C						G G	G				J	ل ل	J	J	J	J N		J	J	J	J	J	M			
	0.022				U						G	G				J	J	J	J	N	IN		J	J	J	J	J	M			
	0.000									G	G	G				J	J	J	J	N			J	J	J	J	J	M			
	0.068									G	G	G				J	Ĵ	ĴĴ	Ĵ	N			Ĵ	Ĵ	Ĵ	Ĵ	Ĵ	P			
	0.10					С			G	G	G	G				J	J	J	J	N			J	J	J	J	M	Р			
	0.15							G	G							J	J	J	Ν	N			J	J	J	J	Q				
	0.22							G	G		J*					J	J	N	N	Ν			J	J	J	J	Q				
	0.33															Ν	Ν	N	Ν	N			J	J	M	P	Q				
	0.47										J*					N	N	N	N	N			M	M	M	P	Q				
	0.68								1+	1+						N	N	N					M	M	Q	Q	Q				
	1.0 1.5								J*	J*						N	N	N					M P	M Q	QQ	Q	Q				
	1.5 2.2							*										P*					Q	Q	Q						
	3.3		-		<u> </u>			J														<u> </u>	Q	Q	Q			\vdash			
	4.7															P*	P*						Q*	Q*	Q*						
	10														P*								Q*	Q*		1					
	22																					Q*									
	47				1																										
	100																														
	WVDC	10	16	25	16	25		6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	500		
	SIZE		0201			0402		0603					0805										12	06							
Latter	Δ		<u></u>		Г						K		N.4		NI		D		0		V		V		7	1					
Letter Max.	A 0.33	-	C 0.56		E G J 0.71 0.90 0.94				K M 1.02 1.27 1				N 1.40		P .52		Q .78		X .29	Y Z 2.54 2.79											
Max. Thickness	(0.013)		0.56).022)		0.71).028)		0.90).035)		0.94).037)		1.02).040)		1.27				.52		.78 070)		.29 090)		.100)		.79 110)						
THICKNESS	(0.013)	((5.022)	`	,	((1.033)	(0	1.037)	((5.040)	(0	.000)	0)	.000)					(0.	090)	(0.	. 100)	(0.	110)	-					
				P	PAPER												EMBOSSED														

*Optional Specifications - Contact factory

Capacitance Range

PREFERRED SIZES ARE SHADED

SIZ	ZE				1210					18	812		18	25		22	2225				
Solde	erina			F	Reflow On	v				Reflo	w Only		Reflow	/ Onlv		Reflo	Reflow Only				
Packa					er/Embos	/					bossed		All Emb	,		All Em	All Embossed				
(L) Length	mm				3.20 ± 0.20						± 0.30		4.50 ± (0.177 ±			5.70	5.72 ± 0.25				
	(in.) mm	(0.126 ± 0.008) 2.50 ± 0.20								(0.177 ± 0.012) 3.20 ± 0.20						(0.225	(0.225 ± 0.010) 6.35 ± 0.25				
(W) Width	(in.)	(0.098 ± 0.008)								(0.126	± 0.008)		6.40 ± (0.252 ±	0.016)		(0.197		(0.250 ± 0.010)			
(t) Terminal	mm (in.)				0.50 ± 0.25 .020 ± 0.01						± 0.36 ± 0.014)		0.61 ± (0.024 ±		0.64 ± 0.39 (0.025 ± 0.015)				0.64 ± 0.39		
	(III.) WVDC	10	16	25	50	500	50	100	200	500	50	100	25	50	100	200	(0.025 ± 0.015) 50 100				
Сар	100	10	10			100	200				200				- 20			200			
(pF)	150																		-W-	~	
	220 330															⊢ ◄		\leq		\leq	
	470																(~		\mathcal{D}	1	
	680																\sim				
	1000																	*t*			
	1500 2200			ل ل	M									i.							
	3300	J	J	J	J	J	J	M													
	4700			J	J	M															
	6800	J	J	J	J	J	J	M	K	K						X	X	V			
Cap (µF	0.010 0.015	J J	J	J	JJ	J J	ل ل	M	K K	K K	K K	K P	M M	M M		X X	X X	X X	M M	P P	
(pi)	0.022	J	J	J	J	J	J	Q	ĸ	ĸ	K	P	M	M		X	X	x	M	P	
	0.033	J	J	J	J	J	J	Q	K	K	K	Х	М	М		Х	Х	Х	М	Р	
	0.047 0.068	J J	J	J	J	J J	J M		K K	K K	K K	Z	M M	M M		X	X X	X X	M M	P	
	0.000	J	J	J	J	J	M		K	K	K	Z	M	M		X	X	X	M	P	
	0.15	J	J	J	J	Μ	Z		ĸ	ĸ	P		M	M		X	Х	X	M	Р	
	0.22	J	J	J	J	P	Z		K	K	P		М	M		X	X	X	M	P	
	0.33 0.47	J M	J	J	J	Q Q			K K	M	X		M M	M M		X X	X X	X	M M	P P	
	0.68	M	M	P	X	X			M	Q			M	P		X	X	~	M	P	
	1.0	N	N	P	Х	Z			М	Х			М	Р		Х	Х		М	Р	
	1.5 2.2	N X	N X	ZZ	ZZ	Z Z			Z Z	Z Z			М			X X	X X		M M	Х	
	3.3	X	X	Z	Z	2			Z	2						X	Z		IVI	<u> </u>	
	4.7	Х	X	Z	Z				Z							Х	Z			1	
	10	Z	Z	Z*											7	Z				 	
	22 47	Z*	Z*												Z					1	
100																					
	WVDC	10	16	25	50	100	200	500	50	100	200	500	50	100	25	50	100	200	50	100	
SIZ	ZE	1210							18	812		18	25		22	220		22	.25		
Letter	A	C	;	E	G J K				М	1	N	Р	Q		X	Y	Z				
Max.	0.33	0.5		0.71	0.90	0.		1.02	1.27		40	1.52	1.78		29	2.54	2.79)			
Thickness		(0.0		(0.028)	(0.035)	(0.0		(0.040)	(0.050		055)	(0.060)	(0.070)		090)	(0.100)	(0.110				
		PAPER										EMBC	DSSED								

*Optional Specifications – Contact factory